

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in this application:

LISTING OF CLAIMS:

Claims 1 to 27. (Canceled).

28. (Currently Amended) A micropump, comprising:
a pump chamber bordered by a cover plate and a pump diaphragm; and
[[a]] the pump diaphragm held on a base plate, a fluid being able to be sucked in via an intake and being able to be passed out via an outlet by a movement of the pump diaphragm;
wherein the pump diaphragm is formed from a polysilicon layer;
wherein the polysilicon layer has a lesser thickness in predetermined areas,
the predetermined areas, including areas of at least one of the intake, the outlet, and
the pump diaphragm; and
wherein the polysilicon layer is at a distance from the base plate in the
predetermined areas.

29. (Previously Presented) The micropump as recited in claim 28, wherein an intake valve is provided as the intake, the intake valve having an inlet channel that is developed in the base plate, the intake valve being developed as a check valve having a first closing element, the first closing element being developed as a part of the polysilicon layer; and wherein the first closing element is situated above an inlet opening of the inlet channel and covers the inlet opening, and as a sealing seat for the first closing element, an area of the base plate is provided that surrounds the inlet opening.

Claim 30. (Canceled).

31. (Currently Amended) The micropump as recited in claim 29, further comprising:
[[a]] the cover plate; and

an anti-bonding layer inserted between a second closing element of an outlet valve of the outlet and the cover plate, the cover plate being anodically bonded to the second closing element, wherein the second closing element is preloaded as a sealing surface by the anti-bonding layer against the cover plate.

32. (New) The micropump as recited in claim 28, further comprising:
the cover plate; and

an anti-bonding layer inserted between a second closing element of an outlet valve of the outlet and the cover plate, the cover plate being anodically bonded to the second closing element, wherein the second closing element is preloaded as a sealing surface by the anti-bonding layer against the cover plate.